

[54] **CIRCUIT MODULE HOUSING**

[56]

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[**] **Term:** 14 Years

[57] **CLAIM**

The ornamental design for a circuit module housing, as shown and described.

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DESCRIPTION

[22] **Filed:** Oct. 30, 1986

[52] **U.S. Cl.** D13/40

[58] **Field of Search** D13/35, 40, 41, 99;
D14/114; 361/331, 342, 346, 380, 381, 383,
390-395, 397, 399, 400, 413, 415-417, 419, 420;
200/302.1, 193; 439/135, 136, 142, 148, 718,
892, 901; 307/116, 118

FIG. 1 is a top-front-left perspective view of a circuit module housing in accordance with our new design; FIG. 2 is a left-side elevation view thereof; FIG. 3 is a front elevation view thereof; FIG. 4 is a right-side elevation view thereof; FIG. 5 is a back elevation view thereof; FIG. 6 is a top plan view thereof; and FIG. 7 is a bottom plan view thereof.

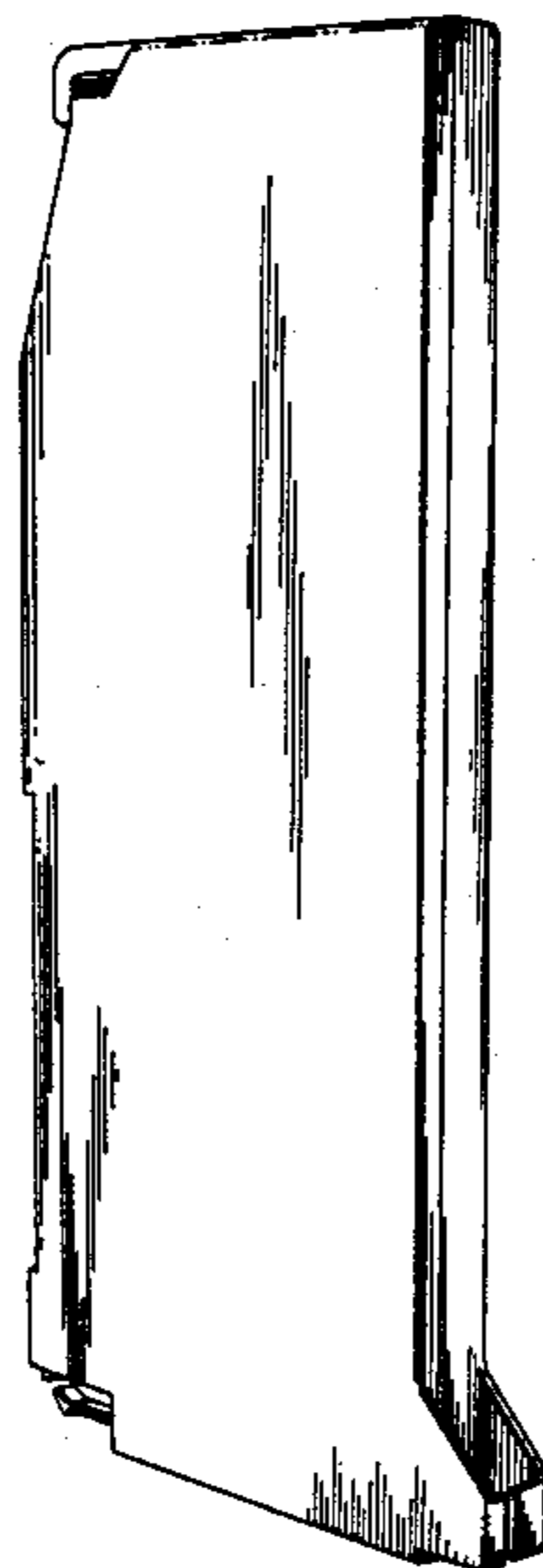


FIG. 1

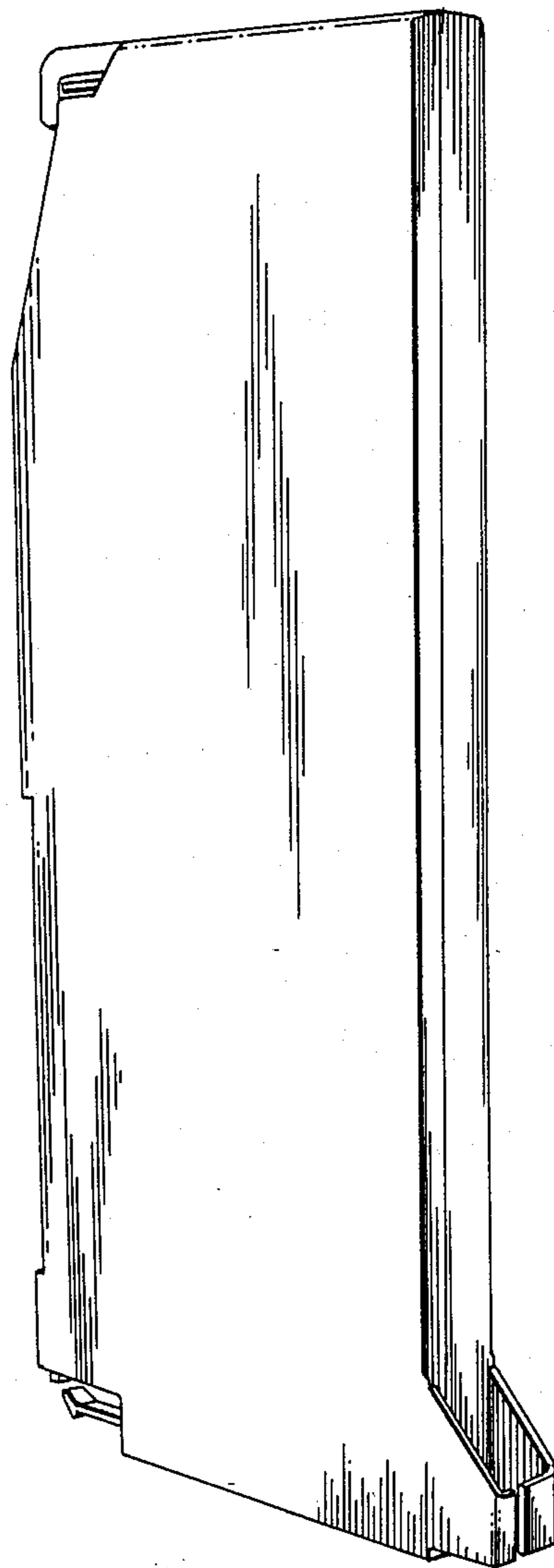


FIG. 2

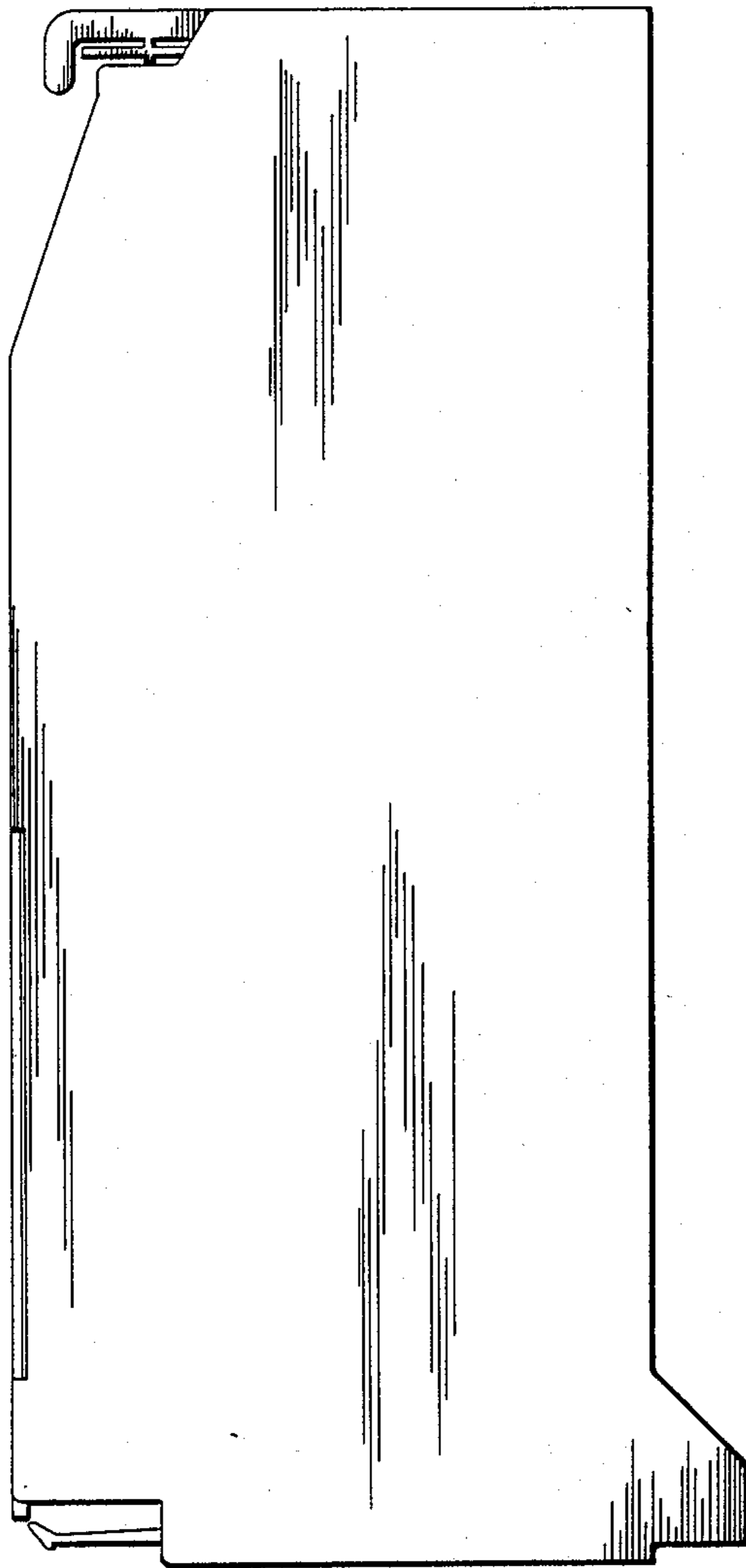


FIG. 3



FIG. 4

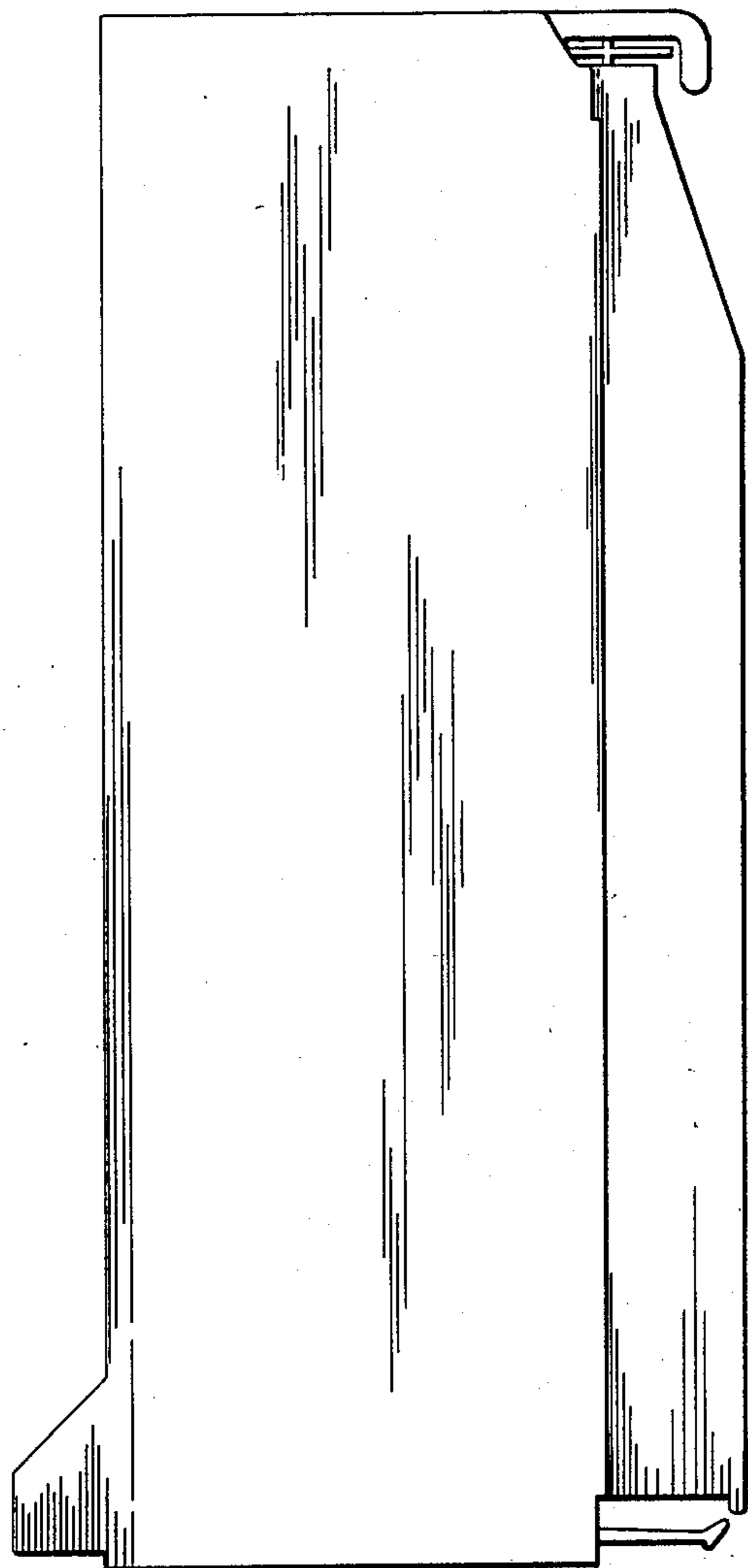


FIG. 5



FIG. 6



FIG. 7

